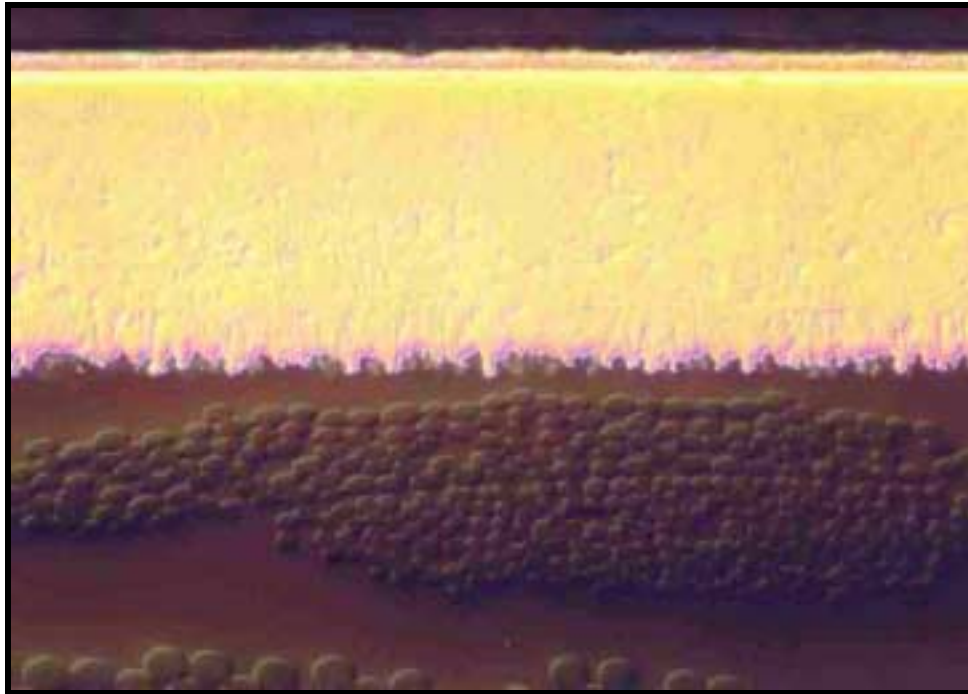


MetPrep Preparation Procedure – No 196



Gold & Copper layers in PCB

	Surface	Abrasive	Pressure		Speed – Dir	Time
Primary Grinding Stage	Paper	P240g SiC	Psi	N	150 – Comp	Until Planar
			5	25		

	Surface	Abrasive	Pressure		Speed – Dir	Time
Additional Grinding Stages	Planocloth H	9 µm (WB) PCD Diamond	Psi	N	250 – Comp	5 mins
			5	25		
	Durasilk	3 µm (WB) PCD Diamond	5	25	250 – Comp	4 mins
	Chrysalis	0.06µm Silco	5	25	100 – Comp	4 mins

	Surface	Abrasive	Pressure		Speed – Dir	Time
Polishing Stage	Multicloth	0.06µm Silco	Psi	N	80 – Comp	2 mins
			3	15		